
SH7670 Group

R01AN0305EJ0101

Rev. 1.01

Using the DMAC to Transfer Data between Memory Areas

Oct. 15, 2010

Summary

This application note provides an example of transferring data between memory areas with the direct memory access controller (DMAC) of the SH7670.

Target Device

SH7670 MCU

Contents

1. Introduction.....	2
2. Description of the Sample Application	3
3. Sample Program Listing.....	9
4. References	15

1. Introduction

1.1 Specifications

- DMAC channel 0 is used to transfer data from the on-chip RAM to external memory. Data are transferred in cycle-stealing mode.
- Auto-request mode (software transfer request) is used for requesting DMA transfer.

1.2 Module Used

- Direct memory access controller (DMAC channel 0)

1.3 Applicable Conditions

MCU	SH7670
Operating Frequency	Internal clock: 200 MHz Bus clock: 66.6 MHz Peripheral clock: 33.3 MHz
Integrated Development Environment	Renesas Electronics High-performance Embedded Workshop Ver.4.03.00
C Compiler	Renesas Electronics SuperH RISC engine Family C/C++ compiler package Ver.9.01 Release 01
Compiler Options	Default setting in the High-performance Embedded Workshop (-cpu=sh2afpu -fpu=single -debug -gbr=auto -global_volatile=0 -opt_range=all -infinite_loop=0 -del_vacant_loop=0 -struct_alloc=1)

1.4 Related Application Notes

For more information, refer to the following application notes:

- SH7670 Group Example of Initialization
- SH7670 Group DMAC Dual Address mode
- SH7670 Group Using the DMAC to Transfer Data to On-chip Peripheral Modules

2. Description of the Sample Application

This sample application employs the direct memory access controller (DMAC) to transfer data from the on-chip RAM to external memory.

2.1 Operational Overview of Module Used

When a DMA transfer request is made, the DMAC starts to transfer data in order of priority of predetermined channels. Then, it continues the transfer operation until transfer end condition is met. It has three transfer request modes: auto request, external request, and on-chip peripheral module request. The bus mode is selectable from burst mode and cycle-stealing mode.

An overview of the DMAC is given in table 1. Also, a block diagram of the DMAC is shown in figure 1.

Table 1 Overview of DMAC

Item	Description
Number of channels	8 (CH0 to CH7) Only 2 channels (CH0 and CH1) can receive external requests.
Address space	4 Gbytes
Length of transfer data	Byte, word (2 bytes), longword (4 bytes), and 16 bytes (longword × 4)
Maximum number of unit transfers	16,777,216 (24 bits)
Address mode	Single address mode and dual address mode
Transfer request	Auto request, external request, and on-chip peripheral module request (SCIF: 6 sources, IIC3: 2 sources, CMT: 2 sources, USB: 2 sources, SSI: 2 sources)
Bus mode	Cycle-stealing mode and burst mode
Priority level	Channel priority fixed mode and round-robin mode
Interrupt request	An interrupt request to the CPU is made when half or all of a transfer process is completed.
External request detection	DREQ input low/high level detection, rising/falling edge detection
Transfer request acknowledge signal/transfer end signal	Active levels for DACK and TEND can be set independently

Note: For details on the DMAC, refer to the section on the direct memory access controller in the *SH7670 Group Hardware Manual* (REJ09B0437).

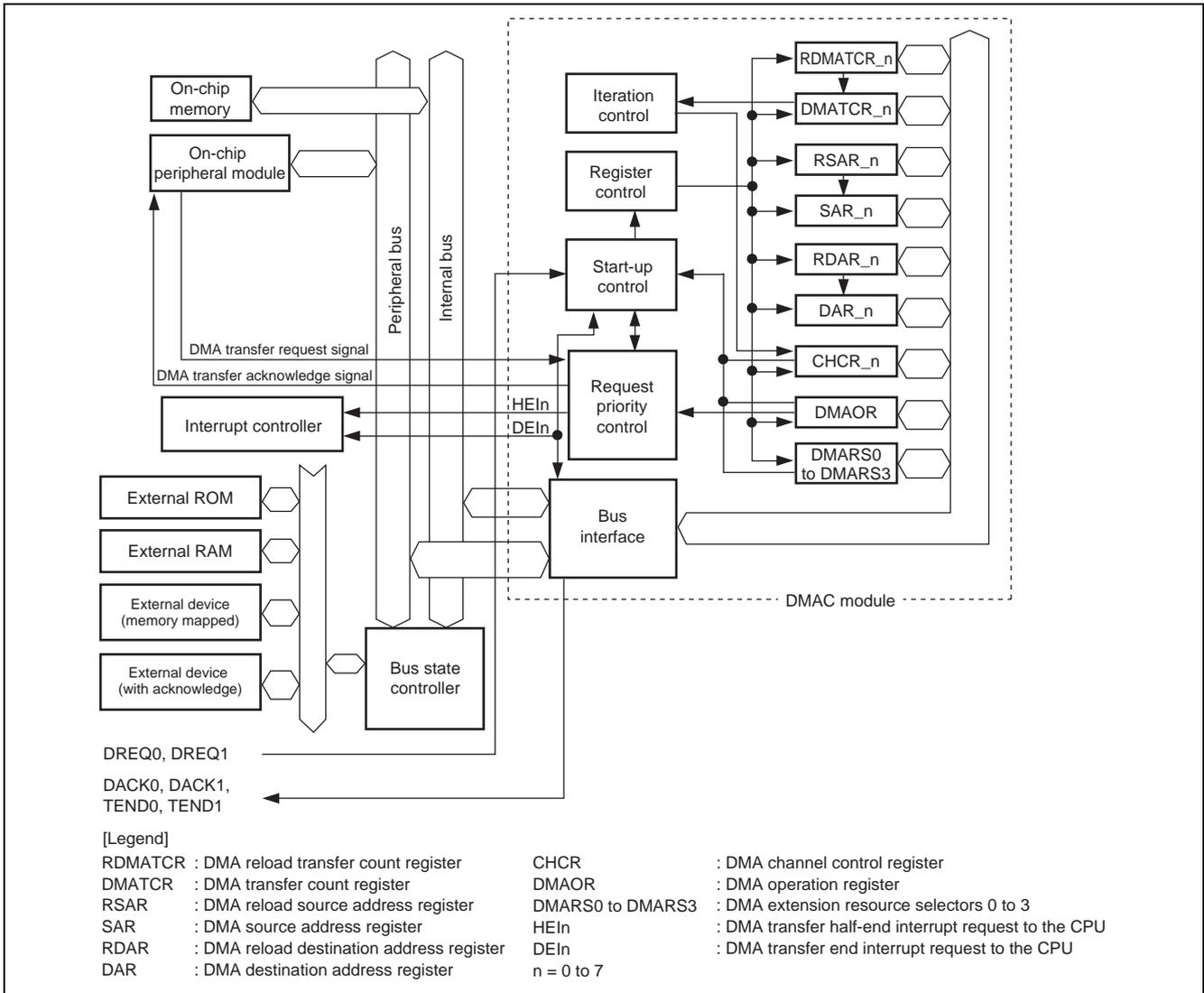


Figure 1 Block Diagram of DMAC

2.2 Procedure for Setting the Module Used

This section describes the procedure for specifying initial settings for transferring data between memory areas with the DMAC. Auto request mode is used for transfer requests. A flowchart of initializing the DMAC is shown in figure 2. For details on registers, refer to the *SH7670 Group Hardware Manual* (REJ09B0437).

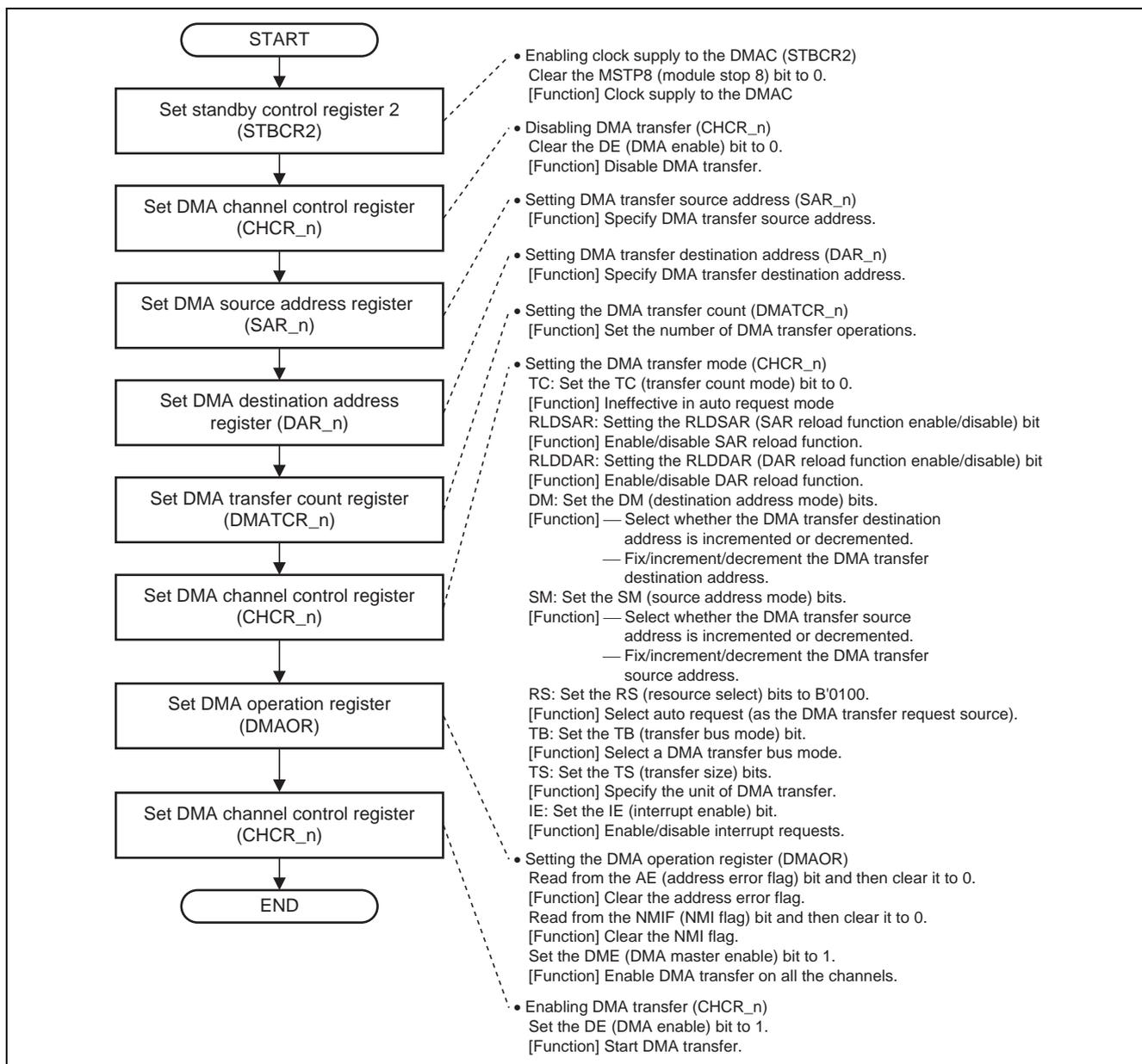


Figure 2 Example of Flow for Initialization of the DMAC

2.3 Operation of the Sample Program

In this sample program, DMAC channel 0 is activated by auto request, and data are transferred from the on-chip RAM to external memory in cycle-stealing mode. In cycle-stealing transfer operation, the DMAC gives the bus mastership to the CPU after each round of transferring a single unit of data. An operation timing of the sample application is shown in figure 3.

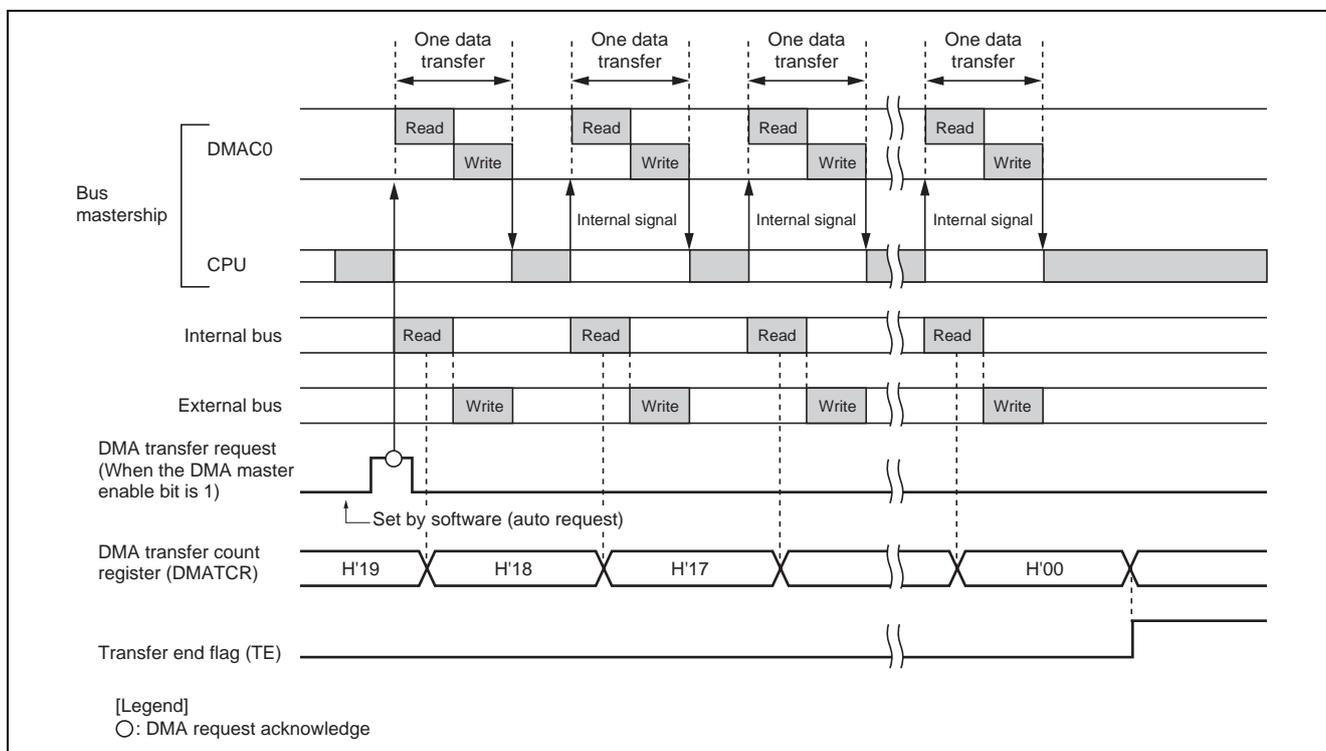


Figure 3 Operation Timing of Sample Application

2.4 Notes on Using the Sample Program

In the reference program, the addresses where the source and destination areas of the transfer start are assigned as absolute addresses for clarity. Ensure that sections used by the user program do not overlap with the source and destination regions that start from the absolute addresses.

2.5 Procedure for Processing by the Sample Program

In this sample program 100-byte data stored in the on-chip RAM are transferred to external memory by DMA transfer. The transfer end flag (TE bit) is used to check whether DMA transfer is completed.

The register settings for the sample program are listed in table 2. The macro definitions used in this sample program are also listed in table 3. A flowchart of the sample program is illustrated in figure 4.

Table 2 Register Settings for Sample Program

Register Name	Address	Setting	Description
Standby control register 2 (STBCR2)	H'FFFE 0018	H'00	MSTP8 = 0: DMAC operates
DMA channel control register_0 (CHCR_0)	H'FFFE 100C	H'0000 0000	DE = 0: Disables DMA transfer
		H'0000 5410	TC = 0: Ineffective in auto-request mode RLDSAR = 0: Disables the SAR reload function RLDDAR = 0: Disables the DAR reload function DM = B'01: Increments the destination address SM = B'01: Increments the source address RS = B'0100: Auto request TB = 0: Cycle-stealing mode TS = B'10: Longword transfer IE = 0: Disables interrupt request
		H'0000 5411	DE = 1: Enables DMA transfer
DMA source address register_0 (SAR_0)	H'FFFE 1000	H'FFF8 4000	Sets start address of transfer source in an on-chip RAM area
DMA destination address register_0 (DAR_0)	H'FFFE 1004	H'2C00 1000	Sets start address of transfer destination in an external memory area*
DMA transfer count register_0 (DMATCR_0)	H'FFFE 1008	H'64	Number of unit transfers: 100 (H'64)
DMA operation register (DMAOR)	H'FFFE 1200	H'0001	DME = 1: Enables DMA transfer on all the channels
DMA extension resource selector0 (DMARS0)	H'FFFE 1300	H'0000	Not used for auto request

Note: * Addresses in external memory area differ with the target board.

Table 3 Macro Definitions Used in Sample Program

Macro Definition	Setting	Description
SDRAM_DST_ADR	H'2C00 1000	Start address of SDRAM
SRAM_SRC_ADR	H'FFF8 4000	Start address of on-chip RAM
SIZE	H'64	Number of unit transfers
DMA_SIZE_BYTE	H'0000	Byte transfer
DMA_SIZE_WORD	H'0001	Word transfer
DMA_SIZE_LONG	H'0002	Longword transfer
DMA_SIZE_LONGx4	H'0003	16-byte transfer
DMA_INT_DISABLE	H'0000	DMA transfer end interrupt not in use
DMA_INT_ENABLE	H'0010	DMA transfer end interrupt in use

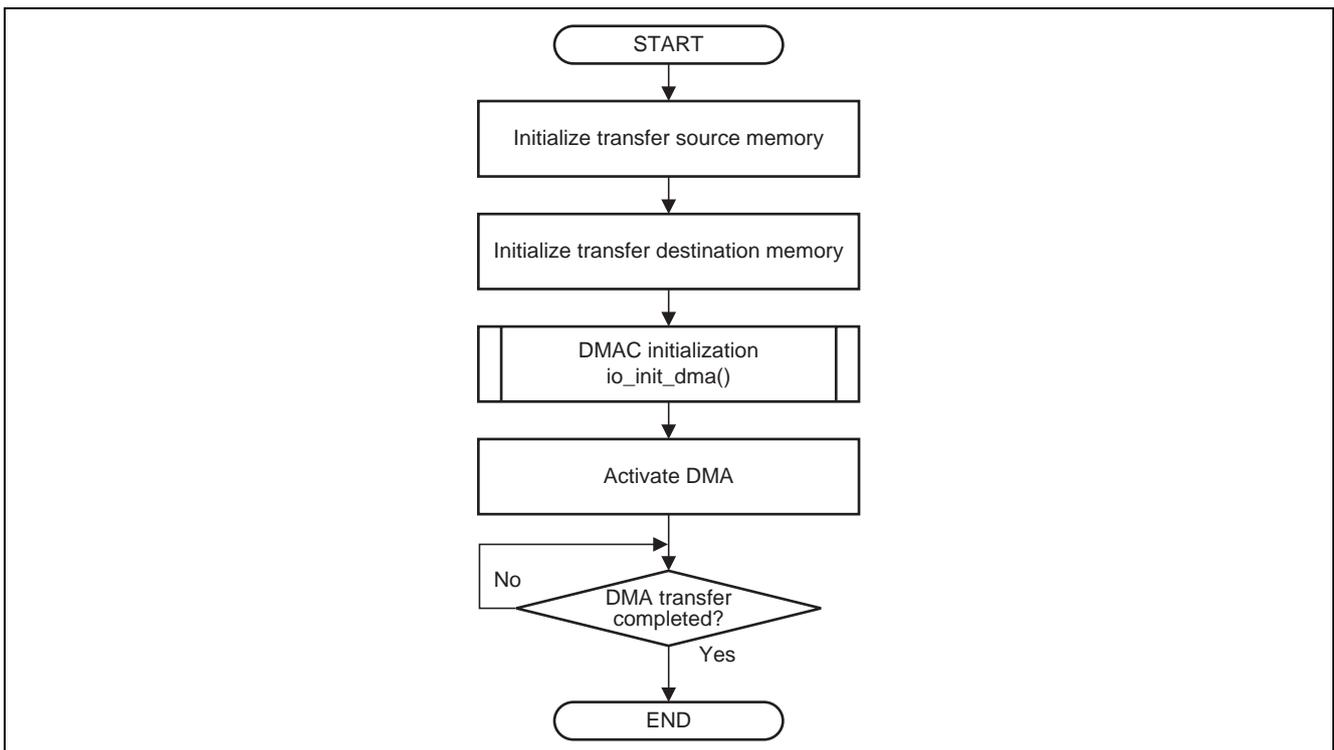


Figure 4 Flow of Processing by the Sample Program

3. Sample Program Listing

3.1 Sample program list "main.c" (1)

```
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26 *   http://www.renesas.com/disclaimer
27 *****/
28 * Copyright (C) 2008(2010) Renesas Electronics Corporation. All rights reserved.
29 * "FILE COMMENT"***** Technical reference data *****
30 *   System Name : SH7671 Sample Program
31 *   File Name   : main.c
32 *   Abstract    : Sample program of DMAC
33 *   Version     : 1.00.01
34 *   Device      : SH7671
35 *   Tool-Chain  : High-performance Embedded Workshop (Ver.4.03.00).
36 *               : C/C++ compiler package for the SuperH RISC engine family
37 *               :                               (Ver.9.01 Release01).
38 *   OS          : None
39 *   H/W Platform: M3A-HS71(CPU board)
40 *   Description :
41 *****/
42 *   History     : Apr.24,2008 ver.1.00.00
43 *               : Oct.08,2010 ver.1.00.01 Changed the company name and device name
44 * "FILE COMMENT END"*****/
```

3.2 Sample program list "main.c" (2)

```
45  #include <machine.h>
46  #include <stdio.h>
47  #include "iodefine.h"                /* SH7670 iodefine */
48
49  /* ==== symbol definition ==== */
50  #define SDRAM_DST_ADR ((void *)0x2c001000) /* External SDRAM address */
51  #define SRAM_SRC_ADR  ((void *)0xffff84000) /* Internal SRAM address */
52  #define SIZE 100                    /* Transmission bytes */
53  #define DMA_SIZE_BYTE   0x0000u
54  #define DMA_SIZE_WORD   0x0001u
55  #define DMA_SIZE_LONG   0x0002u
56  #define DMA_SIZE_LONGx4 0x0003u
57  #define DMA_INT_DISABLE 0x0000u
58  #define DMA_INT_ENABLE  0x0010u
59  #define DMA_INT (DMA_INT_ENABLE >> 4u)
60
61  /* ==== prototype declaration ==== */
62  void main(void);
63  void io_init_dma(void *src, void *dst, size_t size, unsigned int mode);
64  void io_dma_enable(void);
65  void io_dma_stop(void);
66
```

3.3 Sample program list "main.c" (3)

```

67  /*"FUNC COMMENT"*****
68  * Outline      : Sample program main
69  *-----
70  * Include      : #include "iodefine.h"
71  *-----
72  * Declaration  : void main(void);
73  *-----
74  * Function     : Sample program main
75  *-----
76  * Argument    : void
77  *-----
78  * Return Value : none
79  *-----
80  * Notice      :
81  *"FUNC COMMENT END"*****/
82  void main(void)
83  {
84      int i;
85      volatile unsigned char *ptr;
86
87      /* ==== Initialize source memory ==== */
88      ptr = SRAM_SRC_ADR;
89      for(i=0; i < SIZE; i++){
90          *ptr++ = 0x55;
91      }
92
93      /* ==== Initialize destination memory ==== */
94      ptr = SDRAM_DST_ADR;
95      for(i=0; i < SIZE; i++){
96          *ptr++ = 0;
97      }
98
99      /* ==== Setting of DMAC ==== */
100     io_init_dma(SRAM_SRC_ADR, SDRAM_DST_ADR, SIZE, DMA_SIZE_LONG | DMA_INT_DISABLE);
101
102     /* ---- DMA start ---- */
103     io_dma_enable();
104
105     /* ---- DMA stop ---- */
106     io_dma_stop();
107
108     while(1){
109         /* Program end */
110     }
111 }
112

```

3.4 Sample program list "main.c" (4)

```

113  /*"FUNC COMMENT"*****
114  * Outline      : Initialization for data transfer between memory devices by DMAC
115  *-----
116  * Include      : #include "iodefine.h"
117  *-----
118  * Declaration  : void io_init_dma(void *src, void *dst, size_t size, unsigned int mode);
119  *-----
120  * Function     : The DMAC transfers the amount of data specified by "size"
121  *               : from the source address "src" to the destination address "dst".
122  *               : Auto request mode is used to transfer data.
123  *               : Transfer size and use or non-use of interrupts are specified
124  *               : for the "mode".
125  *-----
126  * Argument     : void *src          ; Source address
127  *               : void *dst         ; Destination address
128  *               : size_t size       ; Size of data for transfer (byte)
129  *               : unsigned int mode ; Combos of the transfer and the following modes
130  *               :                   are obtained by logical OR.
131  *               :     DMA_SIZE_BYTE (0x0000) Transfer in units of byte
132  *               :     DMA_SIZE_WORD (0x0001) Transfer in units of word
133  *               :     DMA_SIZE_LONG (0x0002) Transfer in units of longword
134  *               :     DMA_SIZE_LONGx4(0x0003) 16-byte transfer
135  *               :     DMA_INT_DISABLE(0x0000) DMA transfer end interrupt is not in use.
136  *               :     DMA_INT_ENABLE (0x0010) DMA transfer end interrupt is in use.
137  *-----
138  * Return Value : none
139  *-----
140  * Notice       : Operation is not guaranteed when the source/destination address is not
141  *               : on a boundary corresponding to the transfer size.
142  *               : If interrupts are to be used, the interrupt routines must be registered.
143  *"FUNC COMMENT END"*****/
144  void io_init_dma(void *src, void *dst, size_t size, unsigned int mode)
145  {
146      unsigned int ts;
147      unsigned long ie;
148
149      ts = mode & 0x3u;
150      ie = (mode & 0x00f0u) >> 4u;
151
152      /* ==== Setting of DMAC ==== */
153      /* ==== Setting of power down mode ==== */
154      CPG.STBCR2.BIT.MSTP8 = 0x0u; /* Clear the DMAC module standby mode */
155
156      /* ---- DMA Channel Control Registers (CHCR) ---- */
157      DMAC.CHCR0.BIT.DE = 0u1; /* DMA disable */
158
159      /* ---- DMA Source Address Registers (SAR) ---- */
160      DMAC.SAR0 = (unsigned long)src;
161
162      /* ---- DMA Destination Address Registers (DAR) ---- */
163      DMAC.DAR0 = (unsigned long)dst;
164

```

3.5 Sample program list "main.c" (5)

```
165     /* ---- DMA Transfer Count Registers (DMATCR) ---- */
166     switch(ts){
167     case DMA_SIZE_BYTE:
168         DMAC.DMATCR0 = size;           /* Specify number of unit transfers (1/1) */
169         DMAC.RDMATCR0 = size;
170         break;
171     case DMA_SIZE_WORD:
172         DMAC.DMATCR0 = size >> 1u;    /* Specify number of unit transfers (1/2) */
173         DMAC.RDMATCR0 = size >> 1u;
174         break;
175     case DMA_SIZE_LONG:
176         DMAC.DMATCR0 = size >> 2u;    /* Specify number of unit transfers (1/4) */
177         DMAC.RDMATCR0 = size >> 2u;
178         break;
179     case DMA_SIZE_LONGx4:
180         DMAC.DMATCR0 = size >> 4u;    /* Specify number of unit transfers (1/16) */
181         DMAC.RDMATCR0 = size >> 4u;
182         break;
183     default:
184         break;
185     }
186
187     /* ---- DMA Channel Control Registers (CHCR) ---- */
188     DMAC.CHCR0.LONG = 0x00005400ul | (ts << 3u) | (ie << 2u);
189                                     /* Destination address is incremented */
190                                     /* Source address is incremented */
191                                     /* Auto request */
192                                     /* Cycle-stealing mode */
193                                     /* Transfer size : Longword unit */
194
195     /* ---- DMA Operation Register (DMAOR) ---- */
196     DMAC.DMAOR.WORD &= 0xff9u;       /* AE,NMIF clear */
197
198     if(DMAC.DMAOR.BIT.DME == 0ul){   /* DMA Master Enable */
199         DMAC.DMAOR.BIT.DME = 1ul;
200     }
201 }
202
```

3.6 Sample program list "main.c" (6)

```

203  /*"FUNC COMMENT"*****
204  * Outline      : Activation of DMAC
205  *-----
206  * Include      : #include "iodefine.h"
207  *-----
208  * Declaration  : void io_dma_enable(void);
209  *-----
210  * Function     : Performing DMA transfer
211  *-----
212  * Argument     : void
213  *-----
214  * Return Value : none
215  *-----
216  * Notice      :
217  *"FUNC COMMENT END"*****/
218  void io_dma_enable(void)
219  {
220      /* ---- DMA start ---- */
221      DMAC.CHCR0.BIT.DE = 1ul;          /* DMA enable */
222  }
223
224  /*"FUNC COMMENT"*****
225  * Outline      : Halt of DMAC
226  *-----
227  * Include      : #include "iodefine.h"
228  *-----
229  * Declaration  : void io_dma_stop(void);
230  *-----
231  * Function     : Checking whether the transfer is completed and stopping the DMA transfer
232  *-----
233  * Argument     : void
234  *-----
235  * Return Value : none
236  *-----
237  * Notice      :
238  *"FUNC COMMENT END"*****/
239  void io_dma_stop(void)
240  {
241      /* Transmission end detection */
242      while(DMAC.CHCR0.BIT.TE == 0ul){
243          /* wait TE bit set */
244      }
245      /* ---- DMA stop ---- */
246      DMAC.CHCR0.BIT.DE = 0ul;          /* DMA disable */
247  }
248
249  /* End of File */

```

4. References

- Software Manual
SH-2A/SH2A-FPU Software Manual Rev. 3.00
The latest version of the software manual can be downloaded from the Renesas Electronics website.
- Hardware Manual
SH7670 Group Hardware Manual Rev. 2.00
The latest version of the hardware user's manual can be downloaded from the Renesas Electronics website.

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Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Nov.19.08	—	First edition issued
1.01	Oct.15.10	—	Changed the sample program (AC Switching Characteristics are removed)

General Precautions in the Handling of MPU/MCU Products

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1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable.

When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different type number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different type numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different type numbers, implement a system-evaluation test for each of the products.

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